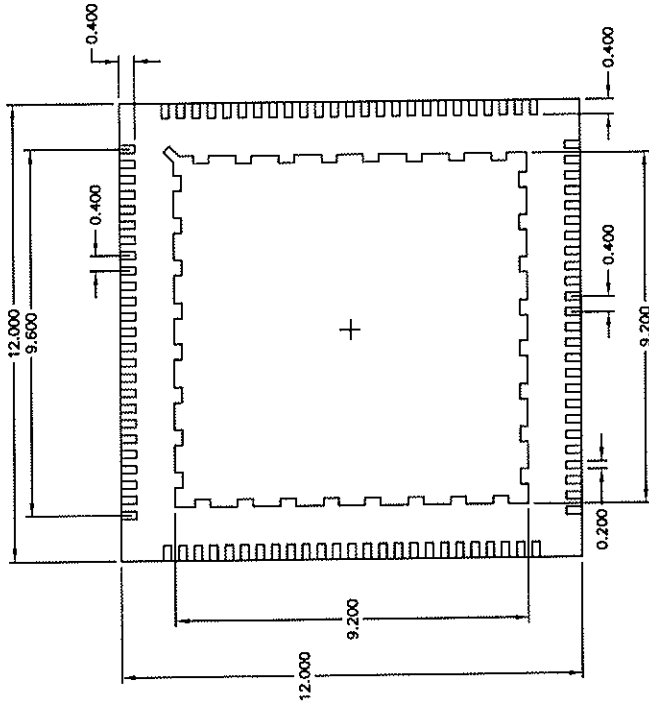


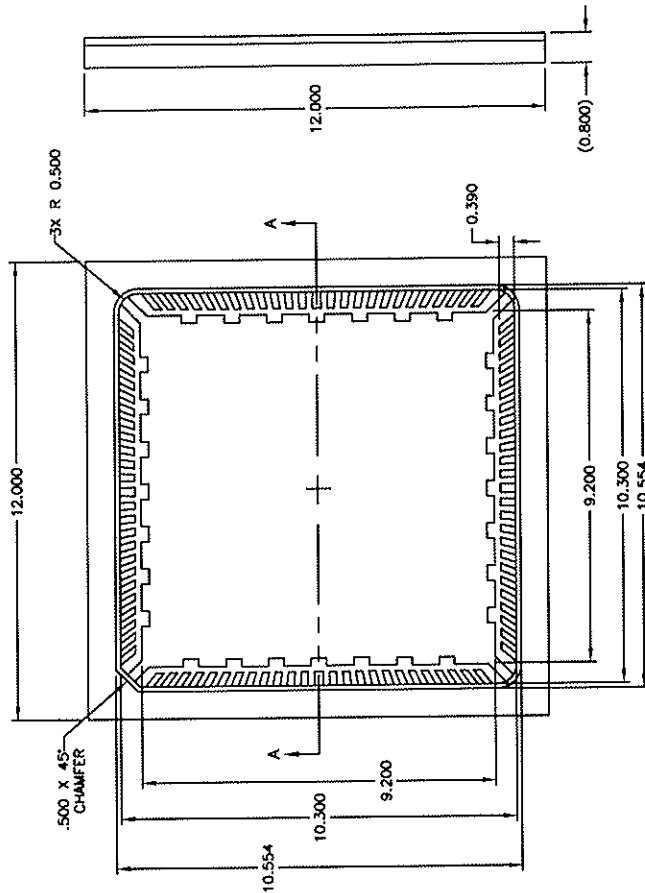
2

1

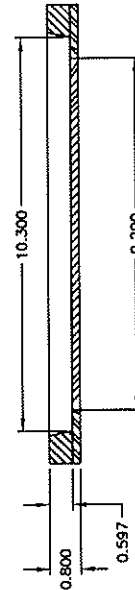
SEMPAK REVISIONS		DATE	DESCRIPTION	APPROVED
ECH NO.	10908	07/20/07	PRODUCTION RELEASE	D.MORRIS



BOTTOM VIEW



TOP VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. LEAD THICKNESS: 0.2030 ± .0076
 5. FRAME THICKNESS: 0.2030 ± .0076
 6. DIE PAD: 9.200mm x 9.200mm.

THIRD ANGLE PROJECTION	DRAWN BY VSK	DATE 07/20/07
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS	APP BY B. FLASKERUD	DATE 07/20/07
TOLERANCES ARE	CUSTOMER	
X.XX ± 0.015		
X.XXX ± 0.050		
ANGLES: ± 1°		
DO NOT SCALE DRAWING	THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO SEMPAC, INC. AND REPRODUCTION OR ISSUE IN ANY FORM IS NOT PERMITTED WITHOUT WRITTEN AUTHORITY FROM SEMPAC, INC.	

SEMPAC, INC.

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 PHONE: (408) 400-9002 FAX: (408) 400-9006

100 LEAD 12mm X 12mm
 MLP Open-Pak™

SIZE A	PART NO. MLP12X12-100-OP-01	REV 3
SCALE NONE	LOAD FILE MLP12X12-100-OP-01-R3.DWG	SHEET 1 OF 1

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